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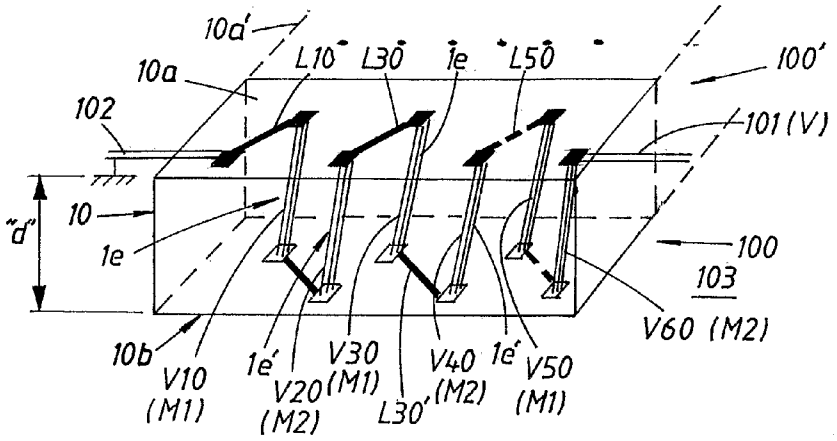
(54) Title: A METHOD FOR PROCESSING A THIN FILM SUBSTRATE



(57) Abstract: The present invention comprises a processed thin film substrate (10) and a method therefore, in order to produce a flexible printed circuit card, having a plurality of microvias going or passing through the thin film substrate and electrically connected along faced-away surfaces, in order to form an electric circuit. A first a number of real nano-tracks are filled with a first material (M1), having good electric properties, for the formation of a first number of, here denominated, first vias (V10, V30, V50), that a second number of real nano-tracks are filled with a second material (M2), having good electric properties, for the formation of a second number of, here denominated, second vias (V20, V40, V60). The first material (M1) and the second material (M2) of said first and second vias (V10-V60) are chosen having mutually different thermoelectric properties. A material surface-applied to the thin film substrate, coated on both sides (10a, 10b) of the thin film substrate (10), is distributed and/or adapted in order to allow the electrical interconnection of first vias, allocated the first material (M1), with second vias, allocated the second material (M2), and that a first via (V10) included in a series connection and a last via (V60) included in the series connection are serially co-ordinated in order to form an electric thermocouple (100) or other circuit arrangement.

WO 2004/098256 A1

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